

Aluminum Finned Heat Sink for Electronic Components

This high-performance aluminum heat sink is designed for efficient heat dissipation in electronic components. Its finned structure maximizes surface area and enhances thermal conductivity.



Overview

High-Performance Thermal Management

This high-performance aluminum heatsink is engineered for superior heat dissipation in critical electronic components. Featuring an advanced finned structure, it maximizes surface area to significantly enhance thermal conductivity and airflow. It provides a reliable and durable cooling solution for CPUs, GPUs, power amplifiers, and other high-heat electronic devices.

Technical Specifications

Material	Aluminum alloy
Design Features	Finned structure, High thermal conductivity, Lightweight, Durable

Applications

Compatible Devices

- CPUs
- GPUs
- Power amplifiers
- General electronic components

Performance Metrics

Cooling Performance

